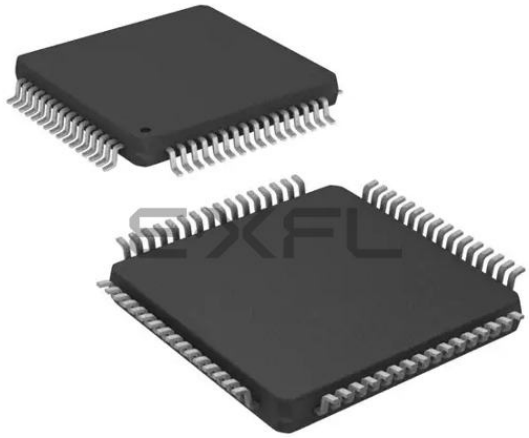
Microchip Technology - DSPIC33EV64GM106T-I/PT Datasheet



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Number of I/O	53
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Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 36x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
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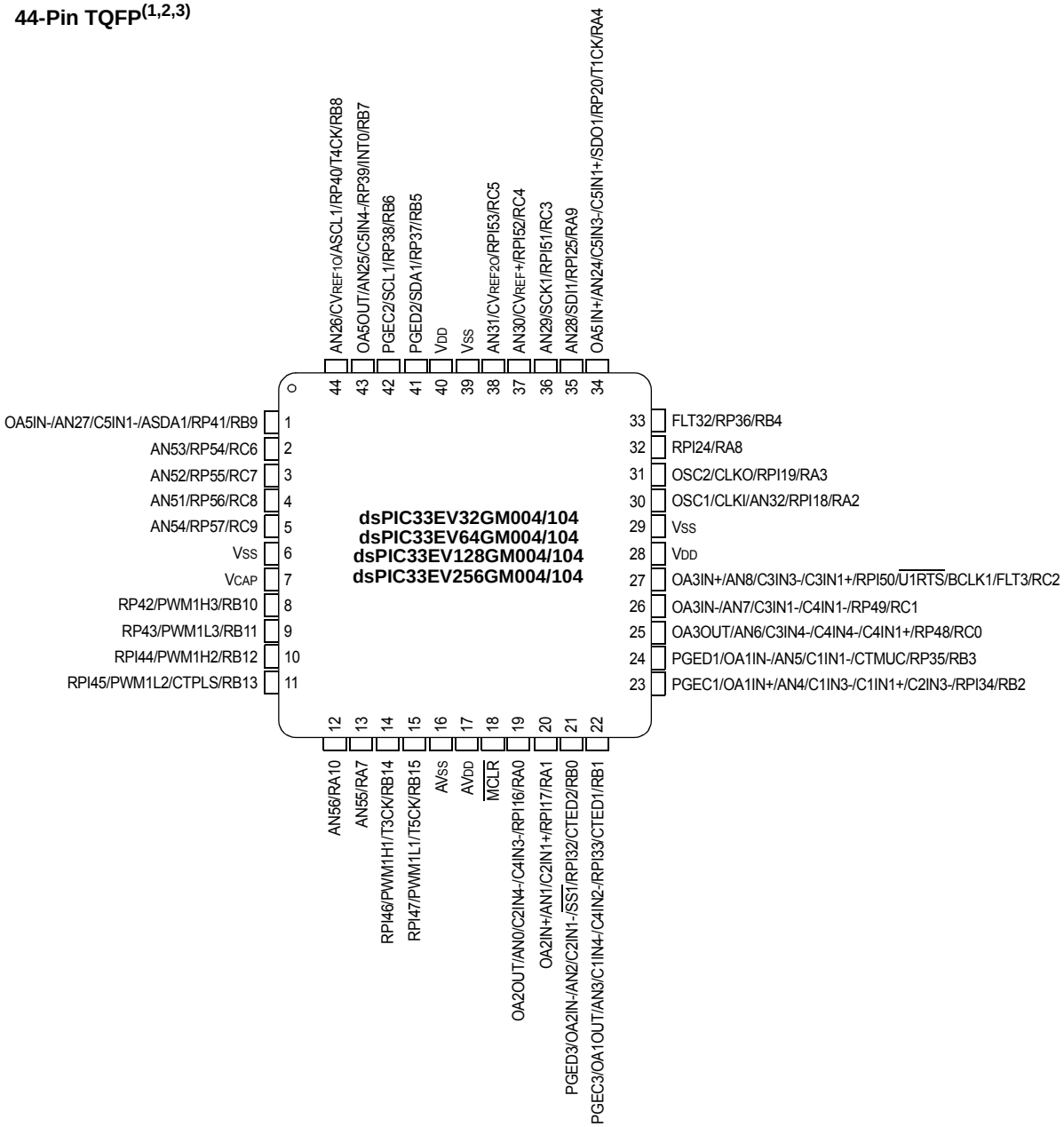
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev64gm106t-i-pt

Pin Diagrams (Continued)

44-Pin TQFP(1,2,3)



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.5 "Peripheral Pin Select (PPS)"** for available peripherals and information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: If the op amp is selected when OPAEN (CMxCON<10>) = 1, the OAx input is used; otherwise, the ANx input is used.

TABLE 4-23: INTERRUPT CONTROLLER REGISTER MAP FOR dsPIC33EVXXXGM00X/10X FAMILY DEVICES

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
IFS0	0800	NVMIF	DMA1IF	AD1IF	U1TXIF	U1RXIF	SPI1IF	SPI1EIF	T3IF	T2IF	OC2IF	IC2IF	DMA0IF	T1IF	OC1IF	IC1IF	INT0IF	0000
IFS1	0802	U2TXIF	U2RXIF	INT2IF	T5IF	T4IF	OC4IF	OC3IF	DMA2IF	—	—	—	INT1IF	CNIF	CMPIF	MI2C1IF	SI2C1IF	0000
IFS2	0804	—	—	—	—	—	—	—	—	—	IC4IF	IC3IF	DMA3IF	C1IF	C1RXIF(1)	SPI2IF	SPI2EIF	0000
IFS3	0806	—	—	—	—	—	—	PSEMIF	—	—	—	—	—	—	—	—	—	0000
IFS4	0808	—	—	CTMUIF	—	—	—	—	—	—	C1TXIF(1)	—	—	—	U2EIF	U1EIF	—	0000
IFS5	080A	PWM2IF	PWM1IF	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IFS6	080C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	PWM3IF	0000
IFS8	0810	—	ICDIF	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IFS10	0814	—	—	I2C1BCIF	—		—	—	—	—	—	—	—	—	—	—	—	0000
IFS11	0816	—	—	—	—	—	ECCSBEIF	SENT2IF	SENT2EIF	SENT1IF	SENT1EIF	—	—	—	—	—	—	0000
IEC0	0820	NVMIE	DMA1IE	AD1IE	U1TXIE	U1RXIE	SPI1IE	SPI1EIE	T3IE	T2IE	OC2IE	IC2IE	DMA0IE	T1IE	OC1IE	IC1IE	INT0IE	0000
IEC1	0822	U2TXIE	U2RXIE	INT2IE	T5IE	T4IE	OC4IE	OC3IE	DMA2IE	—	—	—	INT1IE	CNIE	CMPIE	MI2C1IE	SI2C1IE	0000
IEC2	0824	—	—	—	—	—	—	—	—	—	IC4IE	IC3IE	DMA3IE	C1IE	C1RXIE(1)	SPI2IE	SPI2EIE	0000
IEC3	0826	—	—	—	—	—	—	PSEMIE	—	—	—	—	—	—	—	—	—	0000
IEC4	0828	—	—	CTMUIE	—	—	—	—	—	—	C1TXIE(1)	—	—	—	U2EIE	U1EIE	—	0000
IEC5	082A	PWM2IE	PWM1IE	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IEC6	082C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	PWM3IE	0000
IEC8	0830	—	ICDIE	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IEC10	0834	—	—	I2C1BCIE	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IEC11	0836	—	—	—	—	—	ECCSBEIE	SENT2IE	SENT2EIE	SENT1IE	SENT1EIE	—	—	—	—	—	—	0000
IPC0	0840	—	T1IP2	T1IP1	T1IP0	—	OC1IP2	OC1IP1	OC1IP0	—	IC1IP2	IC1IP1	IC1IP0	—	INT0IP2	INT0IP1	INT0IP0	4444
IPC1	0842	—	T2IP2	T2IP1	T2IP0	—	OC2IP2	OC2IP1	OC2IP0	—	IC2IP2	IC2IP1	IC2IP0	—	DMA0IP2	DMA0IP1	DMA0IP0	4444
IPC2	0844	—	U1RXIP2	U1RXIP1	U1RXIP0	—	SPI1IP2	SPI1IP1	SPI1IP0	—	SPI1EIP2	SPI1EIP1	SPI1EIP0	—	T3IP2	T3IP1	T3IP0	4444
IPC3	0846	—	NVMIP2	NVMIP1	NVMIP0	—	DMA1IP2	DMA1IP1	DMA1IP0	—	AD1IP2	AD1IP1	AD1IP0	—	U1TXIP2	U1TXIP1	U1TXIP0	4444
IPC4	0848	—	CNIP2	CNIP1	CNIP0	—	CMPIP2	CMPIP1	CMPIP0	—	MI2C1IP2	MI2C1IP1	MI2C1IP0	—	SI2C1IP2	SI2C1IP1	SI2C1IP0	4444
IPC5	084A	—	—	—	—	—	—	—	—	—	—	—	—	—		INT1IP<2:0>		0004
IPC6	084C	—	T4IP2	T4IP1	T4IP0	—	OC4IP2	OC4IP1	OC4IP0	—	OC3IP2	OC3IP1	OC3IP0	—	DMA2IP2	DMA2IP1	DMA2IP0	4444
IPC7	084E	—	U2TXIP2	U2TXIP1	U2TXIP0	—	U2RXIP2	U2RXIP1	U2RXIP0	—	INT2IP2	INT2IP1	INT2IP0	—	T5IP2	T5IP1	T5IP0	4444
IPC8	0850	—	C1IP2	C1IP1	C1IP0	—	C1RXIP2(1)	C1RXIP1(1)	C1RXIP0(1)	—	SPI2IP2	SPI2IP1	SPI2IP0	—	SPI2EIP2	SPI2EIP1	SPI2EIP0	4444
IPC9	0852	—	—	—	—	—	IC4IP2	IC4IP1	IC4IP0	—	IC3IP2	IC3IP1	IC3IP0	—	DMA3IP2	DMA3IP1	DMA3IP0	0444
IPC14	085C	—	—	—	—	—	—	—	—	—	PSEMIP<2:0>			—	—	—	—	0040
IPC16	0860	—	—	—	—	—	U2EIP2	U2EIP1	U2EIP0	—	U1EIP2	U1EIP1	U1EIP0	—	—	—	—	0440
IPC17	0862	—	—	—	—	—	C1TXIP<2:0>(1)			—	—	—	—	—	—	—	—	0400

Legend: — = unimplemented, read as '0' Reset values are shown in hexadecimal.

Note 1: This feature is available only on dsPIC33EVXXXGM10X devices.

TABLE 4-24: OUTPUT COMPARE REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
OC1CON1	0900	—	—	OCSIDL	OCTSEL2	OCTSEL1	OCTSEL0	—	—	ENFLTA	—	—	OCFLTA	TRIGMODE	OCM2	OCM1	OCM0	0000
OC1CON2	0902	FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0	000C
OC1RS	0904	Output Compare 1 Secondary Register																xxxx
OC1R	0906	Output Compare 1 Register																xxxx
OC1TMR	0908	Output Compare 1 Timer Value Register																xxxx
OC2CON1	090A	—	—	OCSIDL	OCTSEL2	OCTSEL1	OCTSEL0	—	—	ENFLTA	—	—	OCFLTA	TRIGMODE	OCM2	OCM1	OCM0	0000
OC2CON2	090C	FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0	000C
OC2RS	090E	Output Compare 2 Secondary Register																xxxx
OC2R	0910	Output Compare 2 Register																xxxx
OC2TMR	0912	Output Compare 2 Timer Value Register																xxxx
OC3CON1	0914	—	—	OCSIDL	OCTSEL2	OCTSEL1	OCTSEL0	—	—	ENFLTA	—	—	OCFLTA	TRIGMODE	OCM2	OCM1	OCM0	0000
OC3CON2	0916	FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0	000C
OC3RS	0918	Output Compare 3 Secondary Register																xxxx
OC3R	091A	Output Compare 3 Register																xxxx
OC3TMR	091C	Output Compare 3 Timer Value Register																xxxx
OC4CON1	091E	—	—	OCSIDL	OCTSEL2	OCTSEL1	OCTSEL0	—	—	ENFLTA	—	—	OCFLTA	TRIGMODE	OCM2	OCM1	OCM0	0000
OC4CON2	0920	FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0	000C
OC4RS	0922	Output Compare 4 Secondary Register																xxxx
OC4R	0924	Output Compare 4 Register																xxxx
OC4TMR	0926	Output Compare 4 Timer Value Register																xxxx

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

4.3.3 DATA MEMORY ARBITRATION AND BUS MASTER PRIORITY

EDS accesses from bus masters in the system are arbitrated.

The arbiter for data memory (including EDS) arbitrates between the CPU, the DMA and the MPLAB® ICD module. In the event of coincidental access to a bus by the bus masters, the arbiter determines which bus master access has the highest priority. The other bus masters are suspended and processed after the access of the bus by the bus master with the highest priority.

By default, the CPU is Bus Master 0 (M0) with the highest priority and the MPLAB ICD is Bus Master 4 (M4) with the lowest priority. The remaining bus master (DMA Controller) is allocated to M3 (M1 and M2 are reserved and cannot be used). The user application may raise or lower the priority of the DMA Controller to be above that of the CPU by setting the appropriate bits in the EDS Bus Master Priority Control (MSTRPR) register. All bus masters with raised priorities will maintain the same priority relationship relative to each other (i.e., M1 being highest and M3 being lowest, with M2 in between). Also, all the bus masters with priorities below that of the CPU maintain the same priority relationship relative to each other. The priority schemes for bus masters with different MSTRPR values are listed in Table 4-44.

Figure 4-13 shows the arbiter architecture.

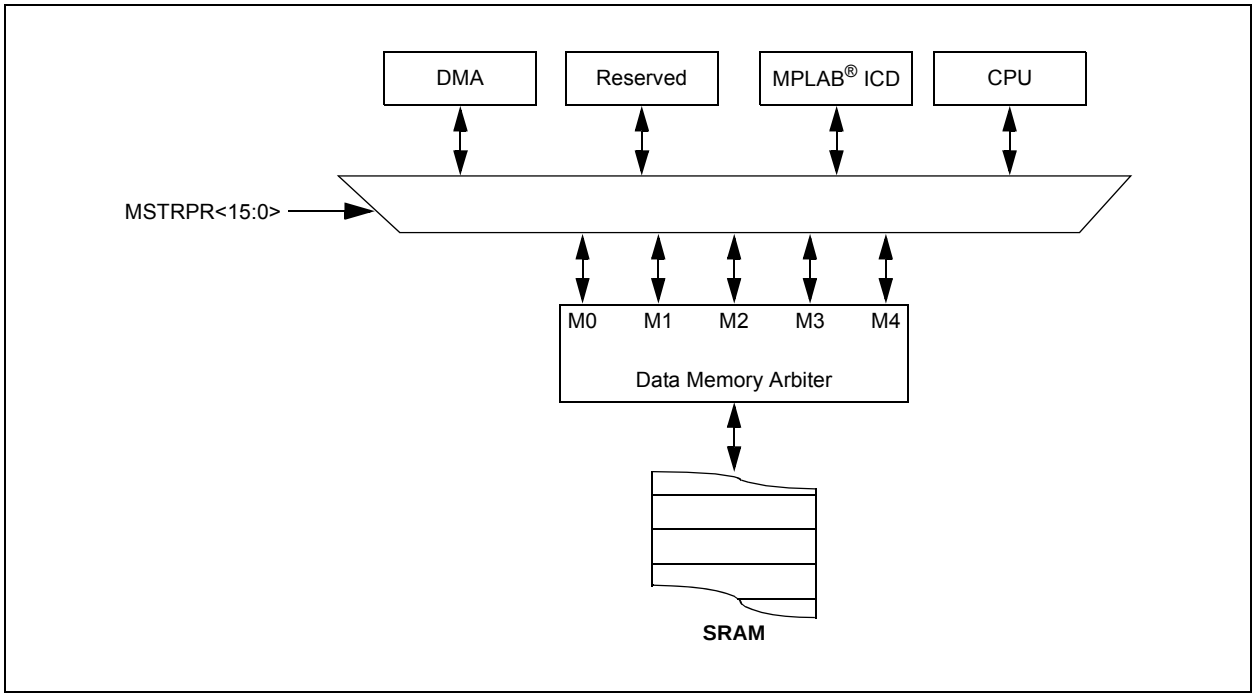
The bus master priority control allows the user application to manipulate the real-time response of the system, either statically during initialization or dynamically in response to real-time events.

TABLE 4-44: DATA MEMORY BUS ARBITER PRIORITY

Priority	MSTRPR<15:0> Bit Setting(1)	
	0x0000	0x0020
M0 (highest)	CPU	DMA
M1	Reserved	CPU
M2	Reserved	Reserved
M3	DMA	Reserved
M4 (lowest)	MPLAB® ICD	MPLAB ICD

Note 1: All other values of MSTRPR<15:0> are reserved.

FIGURE 4-13: ARBITER ARCHITECTURE



5.2 RTSP Operation

RTSP allows the user application to erase a single page of memory, program a row and to program two instruction words at a time. See Table 1 in the **"dsPIC33EVXXXGM00X/10X Product Families"** section for the page sizes of each device.memory array is organized into rows of 64 instructions or 192 bytes. RTSP allows the user application to era

The Flash program memory array is organized into rows of 64 instructions or 192 bytes. RTSP allows the user application to erase a page of program memory, which consists of eight rows (512 instructions) at a time, and to program one row or two adjacent words at a time. The 8-row erase pages and single row write rows are edge-aligned, from the beginning of program memory, on boundaries of 1536 bytes and 192 bytes, respectively. Table 30-13 in **Section 30.0 "Electrical Characteristics"** lists the typical erase and programming times.

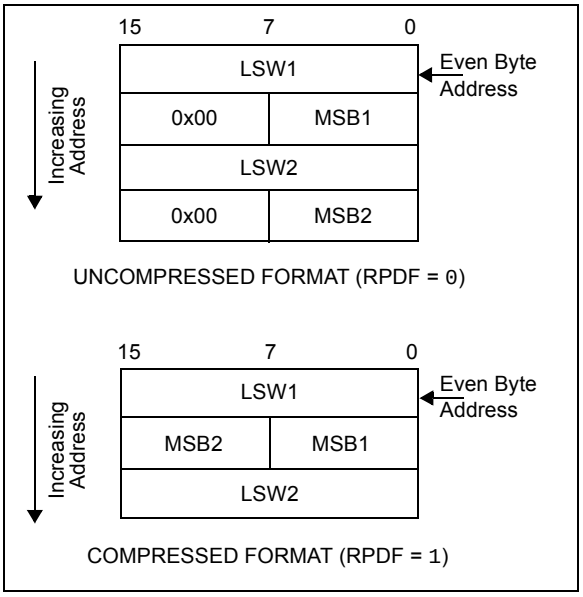
The basic sequence for RTSP word programming is to use the TBLWTL and TBLWTH instructions to load two of the 24-bit instructions into the write latches found in configuration memory space. See Figure 4-1 to Figure 4-5 for write latch addresses. Programming is performed by unlocking and setting the control bits in the NVMCON register.

Row programming is performed by loading 192 bytes into data memory and then loading the address of the first byte in that row into the NVMSRCADR register. Once the write has been initiated, the device will automatically load the write latches and increment the NVMSRCADR and the NVMADR(U) registers until all bytes have been programmed. The RPDF bit (NVMCON<9>) selects the format of the stored data in RAM to be either compressed or uncompressed. See Figure 5-2 for data formatting. Compressed data helps to reduce the amount of required RAM by using the upper byte of the second word for the MSB of the second instruction.

For more information on erasing and programming the Flash memory, refer to **"Flash Programming"** (DS70609) in the *"dsPIC33/PIC24 Family Reference Manual"*.

Note 1:	Before reprogramming either of the two words in a double-word pair, the user must erase the Flash memory page in which it is located.
2:	Before reprogramming any word in a row, the user must erase the Flash memory page in which it is located.

FIGURE 5-2: UNCOMPRESSED/ COMPRESSED FORMAT



5.3 Programming Operations

A complete programming sequence is necessary for programming or erasing the internal Flash in RTSP mode. The processor stalls (waits) until the programming operation is finished. Setting the WR bit (NVMCON<15>) starts the operation and the WR bit is automatically cleared when the operation is finished.

5.3.1 PROGRAMMING ALGORITHM FOR FLASH PROGRAM MEMORY

Programmers can program two adjacent words (24 bits x 2) of program Flash memory at a time on every other word address boundary (0x000002, 0x000006, 0x00000A, etc.). To do this, erase the page that contains the desired address of the location the user wants to change. For protection against accidental operations, the write initiate sequence for NVMKEY must be used to allow any erase or program operation to proceed. After the programming command has been executed, the user application must wait for the programming time until programming is complete. The two instructions following the start of the programming sequence should be NOPs.

Refer to **"Flash Programming"** (DS70609) in the "*dsPIC33/PIC24 Family Reference Manual*" for details and code examples on programming using RTSP.

7.3 Reset Sequence

A device Reset is not a true exception because the interrupt controller is not involved in the Reset process. The dsPIC33EVXXXGM00X/10X family devices clear their registers in response to a Reset, which forces the PC to zero. The device then begins program execution at location, 0x000000. A GOTO instruction at the Reset address can redirect program execution to the appropriate start-up routine.

Note: Any unimplemented or unused vector locations in the IVT should be programmed with the address of a default interrupt handler routine that contains a RESET instruction.

7.4 Interrupt Control and Status Registers

dsPIC33EVXXXGM00X/10X family devices implement the following registers for the interrupt controller:

- INTCON1
- INTCON2
- INTCON3
- INTCON4
- IFSx
- IECx
- IPCx
- INTTREG

7.4.1 INTCON1 THROUGH INTCON4

Global interrupt control functions are controlled from the INTCON1, INTCON2, INTCON3 and INTCON4 registers.

INTCON1 contains the Interrupt Nesting Disable bit (NSTDIS), as well as the control and status flags for the processor trap sources.

The INTCON2 register controls external interrupt request signal behavior and also contains the Global Interrupt Enable bit (GIE).

INTCON3 contains the status flags for the DMT (Dead-man Timer), DMA and DO stack overflow status trap sources.

The INTCON4 register contains the ECC Double-Bit Error (ECCDBE) and Software-Generated Hard Trap (SGHT) status bit.

7.4.2 IFSx

The IFSx registers maintain all of the interrupt request flags. Each source of interrupt has a status bit, which is set by the respective peripherals or external signal and is cleared through software.

7.4.3 IECx

The IECx registers maintain all of the interrupt enable bits. These control bits are used to individually enable interrupts from the peripherals or external signals.

7.4.4 IPCx

The IPCx registers are used to set the Interrupt Priority Level (IPL) for each source of interrupt. Each user interrupt source can be assigned to one of eight priority levels.

7.4.5 INTTREG

The INTTREG register contains the associated interrupt vector number and the new CPU Interrupt Priority Level, which are latched into Vector Number (VECNUM<7:0>) and Interrupt Priority Level bit (ILR<3:0>) fields in the INTTREG register. The new Interrupt Priority Level is the priority of the pending interrupt.

The interrupt sources are assigned to the IFSx, IECx and IPCx registers in the same sequence as they are listed in Table 7-1. For example, the INT0 (External Interrupt 0) is shown as having Vector Number 8 and a natural order priority of 0. Thus, the INT0IF bit is found in IFS0<0>, the INT0IE bit in IEC0<0> and the INT0IP bits in the first position of IPC0 (IPC0<2:0>).

7.4.6 STATUS/CONTROL REGISTERS

Although these registers are not specifically part of the interrupt control hardware, two of the CPU Control registers contain bits that control interrupt functionality. For more information on these registers, refer to **"CPU"** (DS70359) in the *"dsPIC33/PIC24 Family Reference Manual"*.

- The CPU STATUS Register, SR, contains the IPL<2:0> bits (SR<7:5>). These bits indicate the current CPU Interrupt Priority Level. The user software can change the current CPU Interrupt Priority Level by writing to the IPLx bits.
- The CORCON register contains the IPL3 bit which, together with IPL<2:0>, also indicates the current CPU Interrupt Priority Level. IPL3 is a read-only bit so that trap events cannot be masked by the user software.

All Interrupt registers are described in Register 7-3 to Register 7-7.

REGISTER 7-6: INTCON4: INTERRUPT CONTROL REGISTER 4

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	R-0, HS, SC	R-0, HS, SC
—	—	—	—	—	—	ECCDBE(1)	SGHT
bit 7							bit 0

Legend:	HS = Hardware Settable bit	SC = Software Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-2 **Unimplemented:** Read as '0'

bit 1 **ECCDBE:** ECC Double-Bit Error Trap bit(1)
1 = ECC double-bit error trap has occurred
0 = ECC double-bit error trap has not occurred

bit 0 **SGHT:** Software-Generated Hard Trap Status bit
1 = Software-generated hard trap has occurred
0 = Software-generated hard trap has not occurred

Note 1: ECC double-bit error causes a generic hard trap.

REGISTER 9-2: CLKDIV: CLOCK DIVISOR REGISTER(2) (CONTINUED)

bit 4-0 **PLLPRE<4:0>:** PLL Phase Detector Input Divider Select bits (also denoted as 'N1', PLL prescaler)
11111 = Input divided by 33
•
•
•
00001 = Input divided by 3
00000 = Input divided by 2 (default)

Note 1: This bit is cleared when the ROI bit is set and an interrupt occurs.

2: This register resets only on a Power-on Reset (POR).

3: DOZE<2:0> bits can only be written to when the DOZEN bit is clear. If DOZEN = 1, any writes to DOZE<2:0> are ignored.

4: The DOZEN bit cannot be set if DOZE<2:0> = 000. If DOZE<2:0> = 000, any attempt by user software to set the DOZEN bit is ignored.

11.1.1 OPEN-DRAIN CONFIGURATION

In addition to the PORTx, LATx and TRISx registers for data control, port pins can also be individually configured for either digital or open-drain outputs. This is controlled by the Open-Drain Control x register (ODCx) associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The open-drain feature allows the generation of outputs other than VDD by using external pull-up resistors. The maximum open-drain voltage allowed on any pin is the same as the maximum VIH specification for that particular pin.

See Table 30-10 in **Section 30.0 "Electrical Characteristics"** for the maximum VIH specification of each pin.

11.2 Configuring Analog and Digital Port Pins

The ANSELx registers control the operation of the analog port pins. The port pins that are to function as analog inputs or outputs must have their corresponding ANSELx and TRISx bits set. In order to use port pins for I/O functionality with digital modules, such as timers, UARTs, etc., the corresponding ANSELx bits must be cleared.

The ANSELx register has a default value of 0xFFFF. Therefore, all pins that share analog functions are analog (not digital) by default.

Pins with analog functions affected by the ANSELx registers are listed with a buffer type of analog in the Pinout I/O Descriptions table (see Table 1-1 in **Section 1.0 "Device Overview"**).

If the TRISx bit is cleared (output) while the ANSELx bit is set, the digital output level (VOH or VOL) is converted by an analog peripheral, such as the ADC module or comparator module.

When the PORTx register is read, all pins configured as analog input channels are read as cleared (a low level).

Pins configured as digital inputs do not convert an analog input. Analog levels on any pin defined as a digital input (including the ANx pins) can cause the input buffer to consume current that exceeds the device specifications.

11.2.1 I/O PORT WRITE/READ TIMING

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically, this instruction would be a NOP, as shown in Example 11-1.

11.3 Input Change Notification (ICN)

The Input Change Notification function (ICN) of the I/O ports allows devices to generate interrupt requests to the processor in response to a Change-of-State (COS) on selected input pins. This feature can detect input Change-of-States, even in Sleep mode, when the clocks are disabled. Every I/O port pin can be selected (enabled) for generating an interrupt request on a Change-of-State.

Three control registers are associated with the ICN functionality of each I/O port. The CNENx registers contain the ICN interrupt enable control bits for each of the input pins. Setting any of these bits enables an ICN interrupt for the corresponding pins.

Each I/O pin also has a weak pull-up and a weak pull-down connected to it. The pull-ups and pull-downs act as a current source or sink source connected to the pin, and eliminate the need for external resistors when push button or keypad devices are connected. The pull-ups and pull-downs are enabled separately using the CNPUx and the CNPDx registers, which contain the control bits for each of the pins. Setting any of the control bits enables the weak pull-ups and/or pull-downs for the corresponding pins.

Note:	The pull-ups and pull-downs on ICN pins should always be disabled when the port pin is configured as a digital output.

EXAMPLE 11-1: PORT WRITE/READ EXAMPLE

```
MOV   0xFF00, W0   ; Configure PORTB<15:8>
                   ; as inputs
MOV   W0, TRISB    ; and PORTB<7:0>
                   ; as outputs
NOP                ; Delay 1 cycle
BTSS  PORTB, #13   ; Next Instruction
```

NOTES:

REGISTER 22-10: CxCFG2: CANx BAUD RATE CONFIGURATION REGISTER 2

U-0	R/W-x	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x
—	WAKFIL	—	—	—	SEG2PH2	SEG2PH1	SEG2PH0
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SEG2PHTS	SAM	SEG1PH2	SEG1PH1	SEG1PH0	PRSEG2	PRSEG1	PRSEG0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14 **WAKFIL:** Select CAN Bus Line Filter for Wake-up bit
1 = Uses CAN bus line filter for wake-up
0 = CAN bus line filter is not used for wake-up

bit 13-11 **Unimplemented:** Read as '0'

bit 10-8 **SEG2PH<2:0>:** Phase Segment 2 bits
111 = Length is 8 x TQ
•
•
•
000 = Length is 1 x TQ

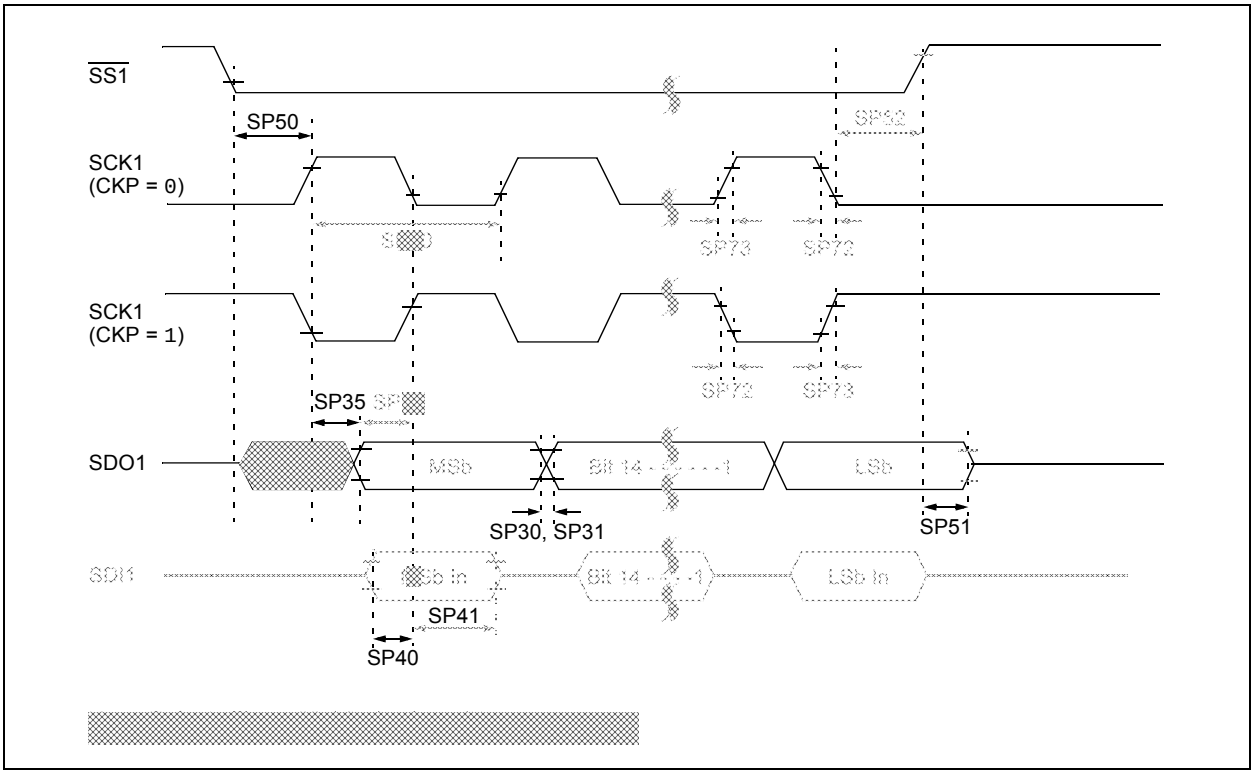
bit 7 **SEG2PHTS:** Phase Segment 2 Time Select bit
1 = Freely programmable
0 = Maximum of SEG1PH<2:0> bits or Information Processing Time (IPT), whichever is greater

bit 6 **SAM:** Sample of the CAN Bus Line bit
1 = Bus line is sampled three times at the sample point
0 = Bus line is sampled once at the sample point

bit 5-3 **SEG1PH<2:0>:** Phase Segment 1 bits
111 = Length is 8 x TQ
•
•
•
000 = Length is 1 x TQ

bit 2-0 **PRSEG<2:0>:** Propagation Time Segment bits
111 = Length is 8 x TQ
•
•
•
000 = Length is 1 x TQ

FIGURE 30-26: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING CHARACTERISTICS



32.2 IIDLE

FIGURE 32-7: TYPICAL/MAXIMUM IIDLE vs. FOSC (EC MODE 10 MHz TO 70 MHz, 5.5V MAX)

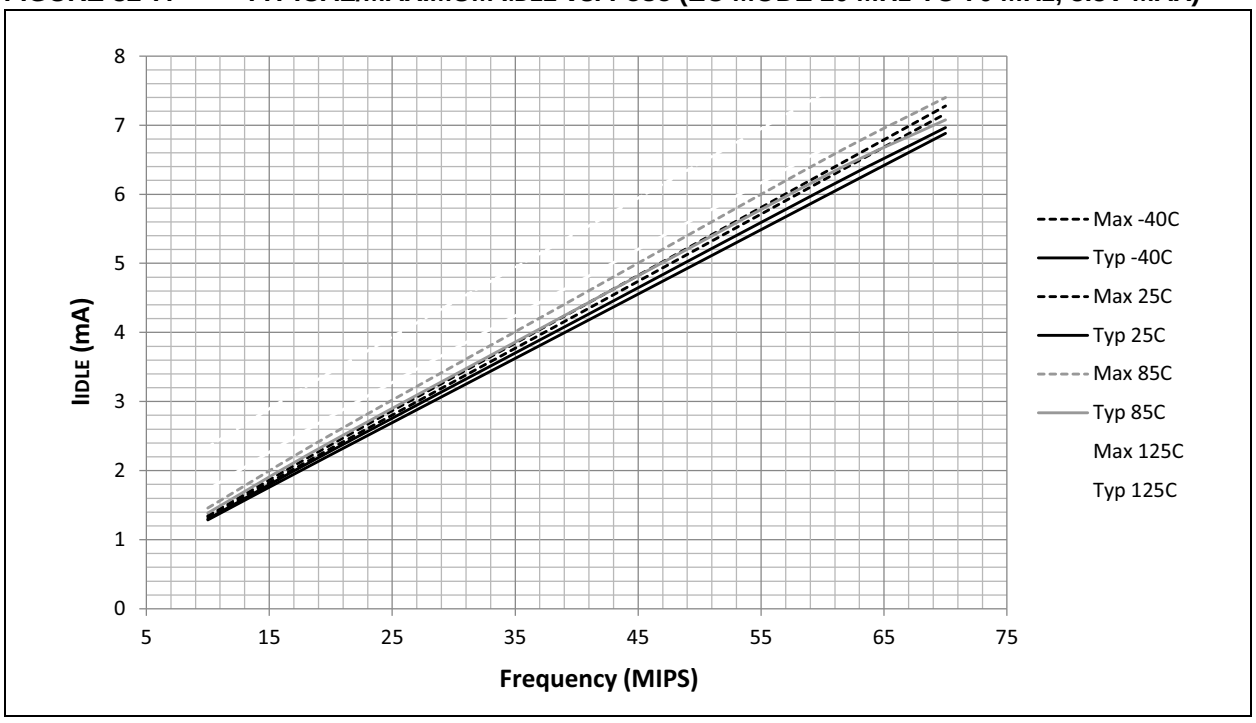
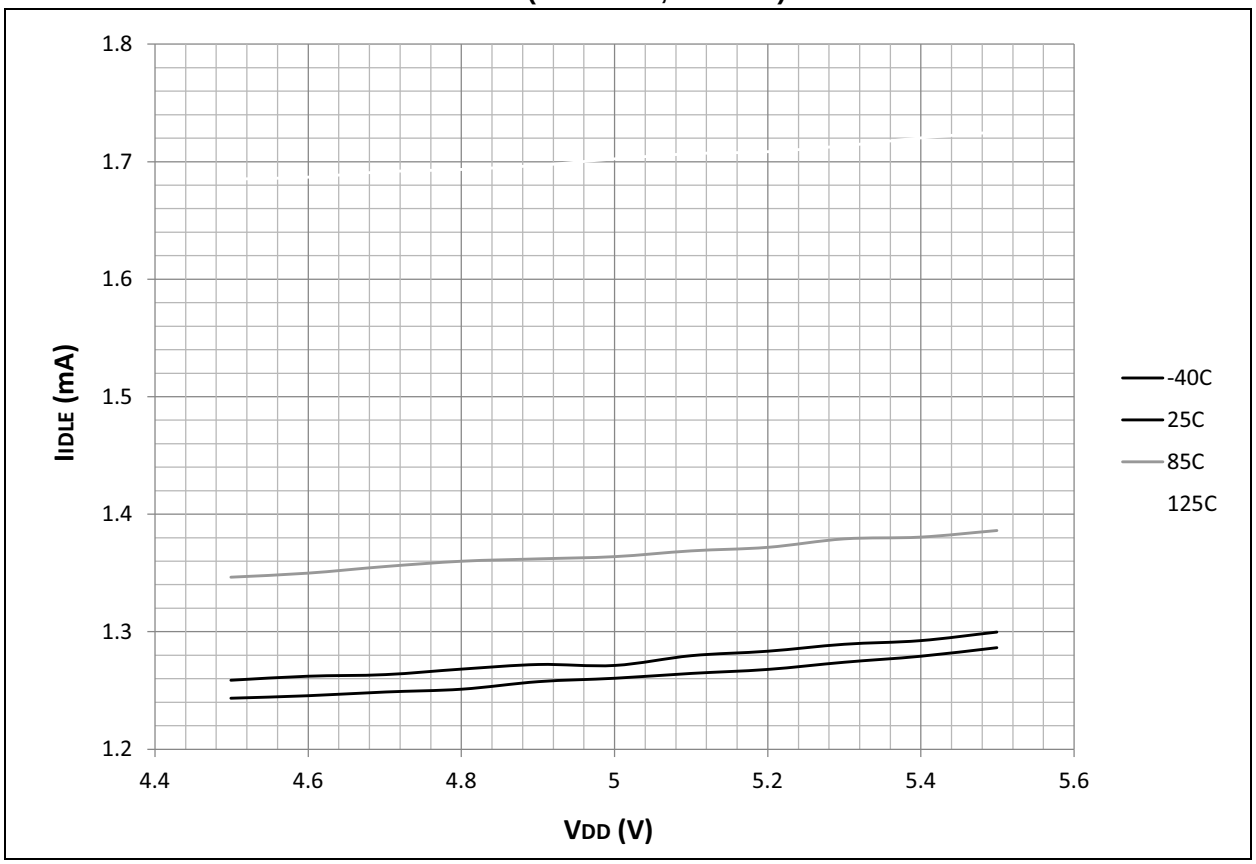
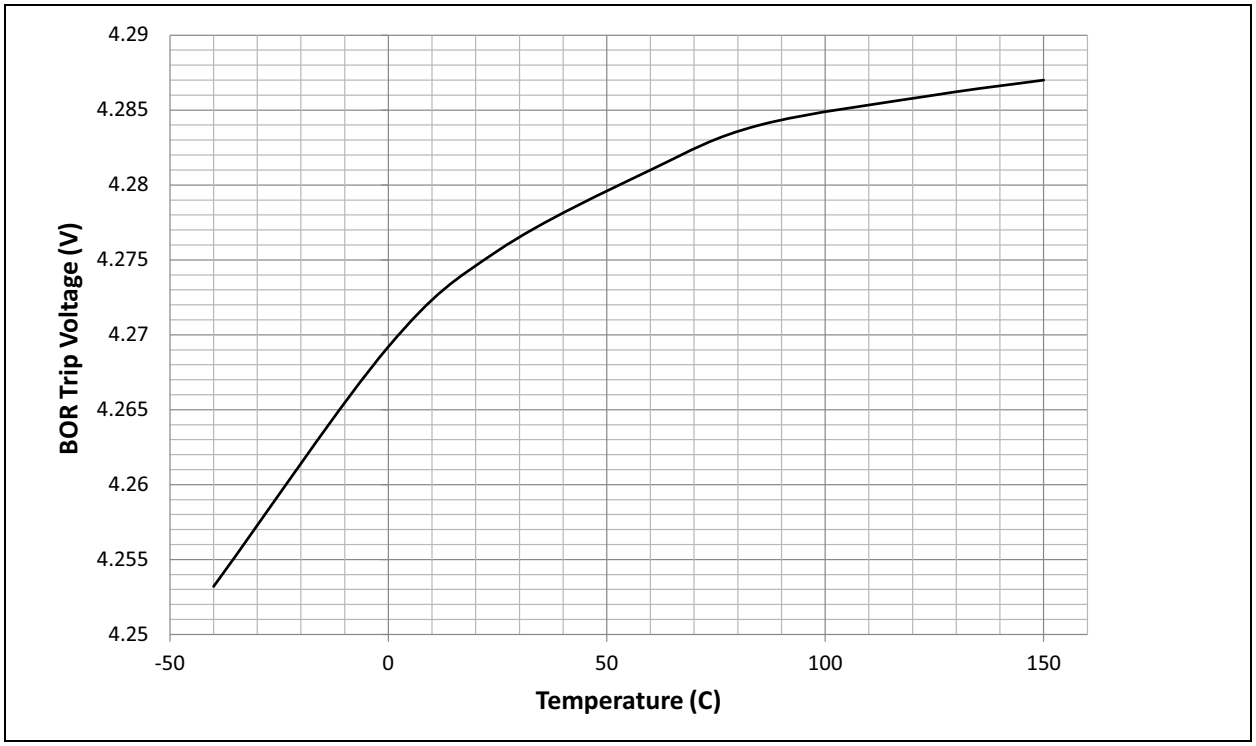


FIGURE 32-8: TYPICAL IIDLE vs. VDD (EC MODE, 10 MIPS)



32.12 VBOR

FIGURE 32-35: TYPICAL BOR TRIP RANGE vs. TEMPERATURE



32.13 RAM Retention

FIGURE 32-36: TYPICAL RAM RETENTION VOLTAGE vs. TEMPERATURE

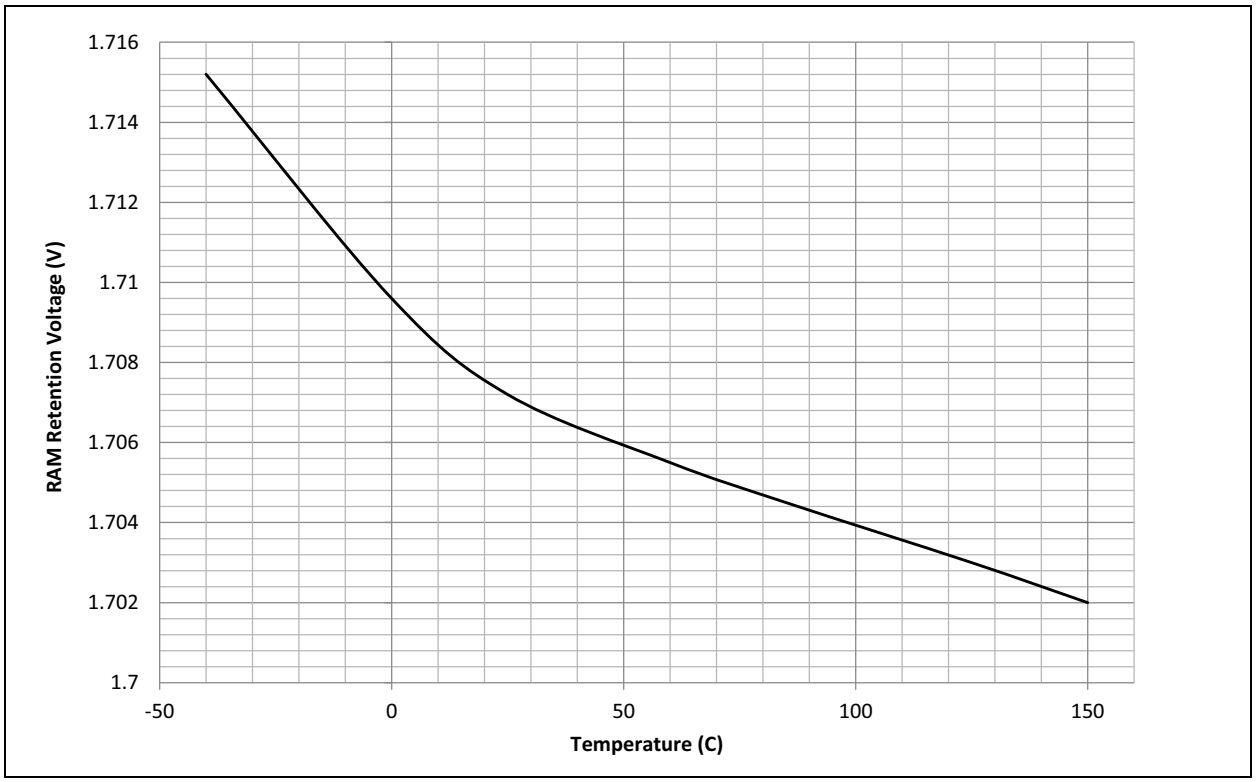


FIGURE 32-43: TYPICAL DNL (V_{DD} = 5.5V, +85°C)

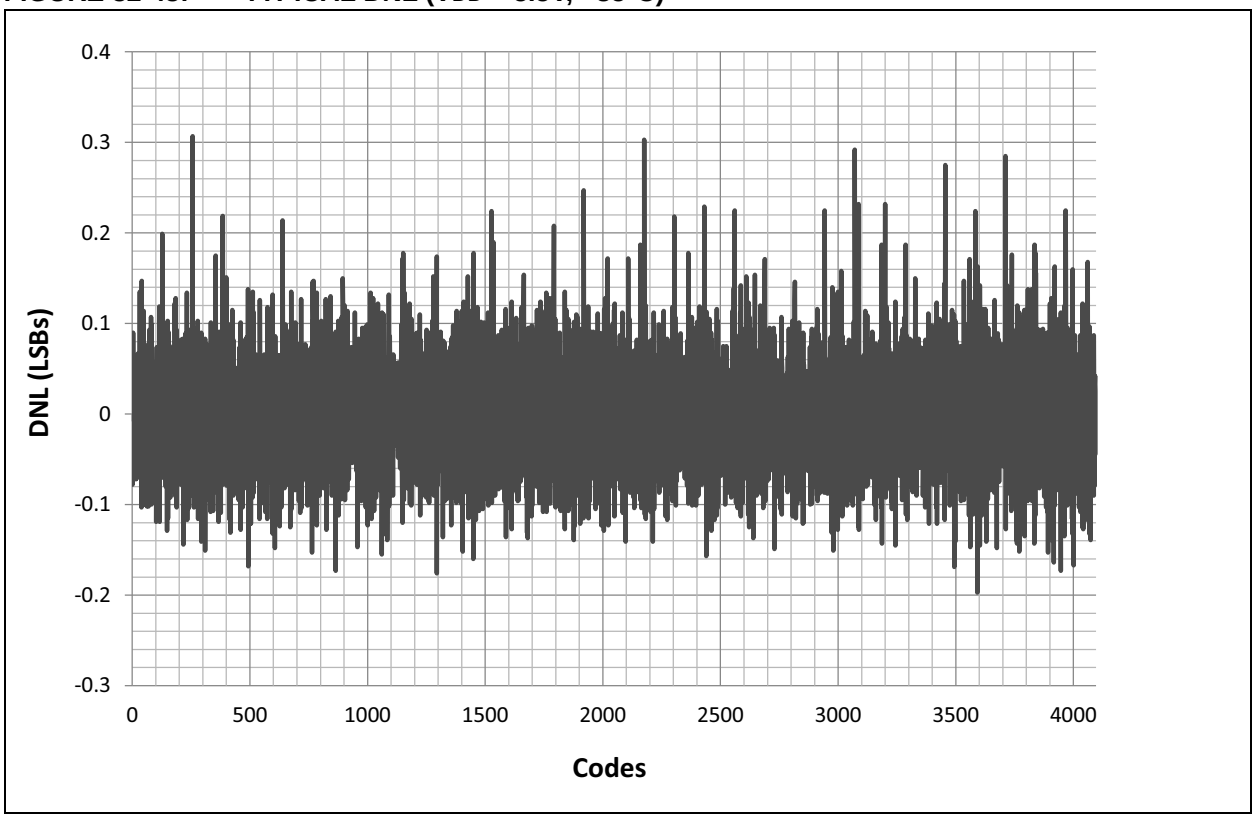
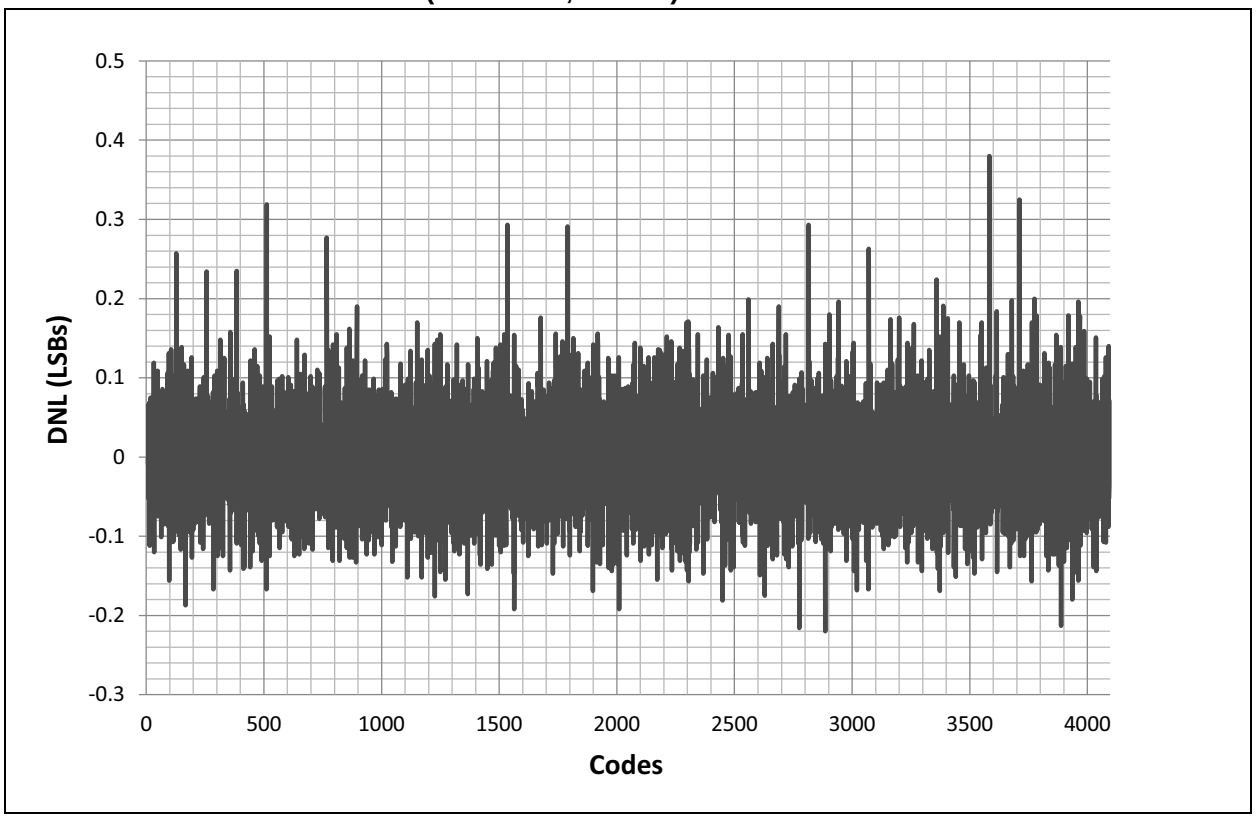


FIGURE 32-44: TYPICAL DNL (V_{DD} = 5.5V, +125°C)



33.3 IDOZE

FIGURE 33-9: TYPICAL IDOZE vs. VDD (DOZE 1:2, 70 MIPS)

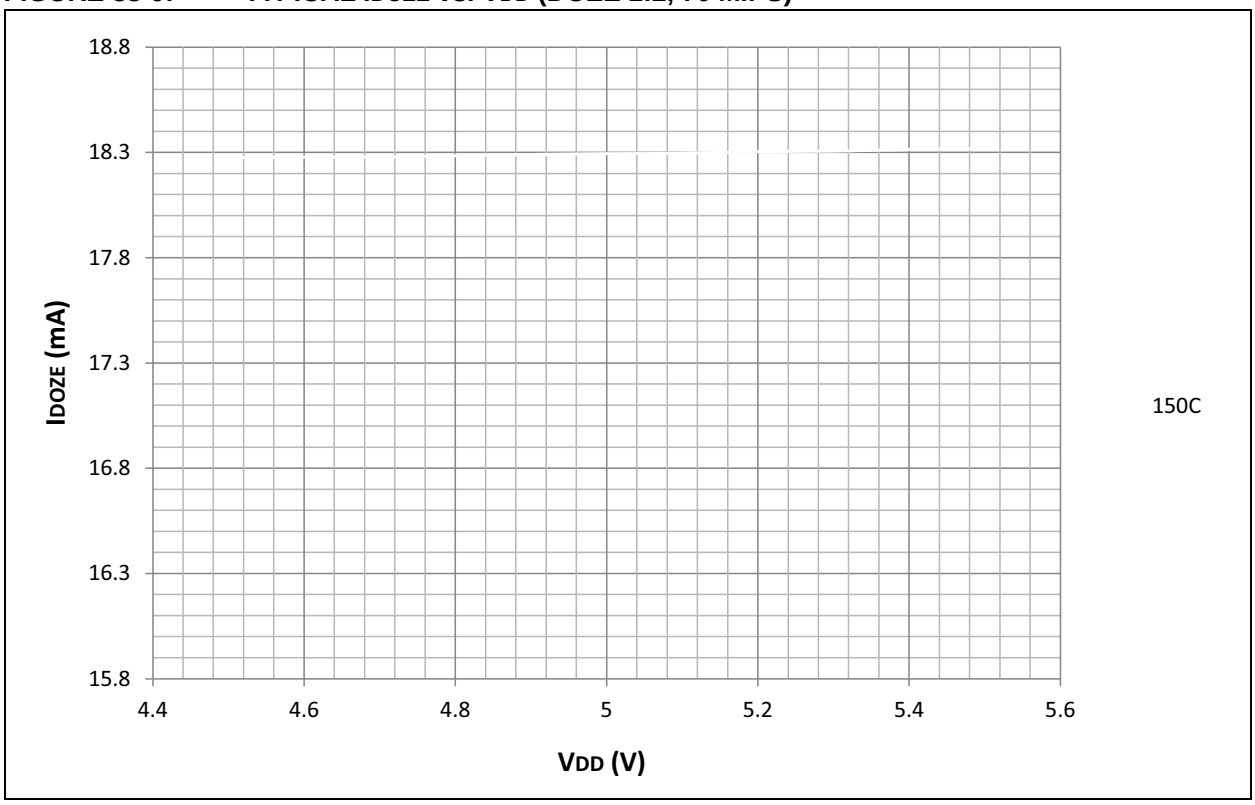
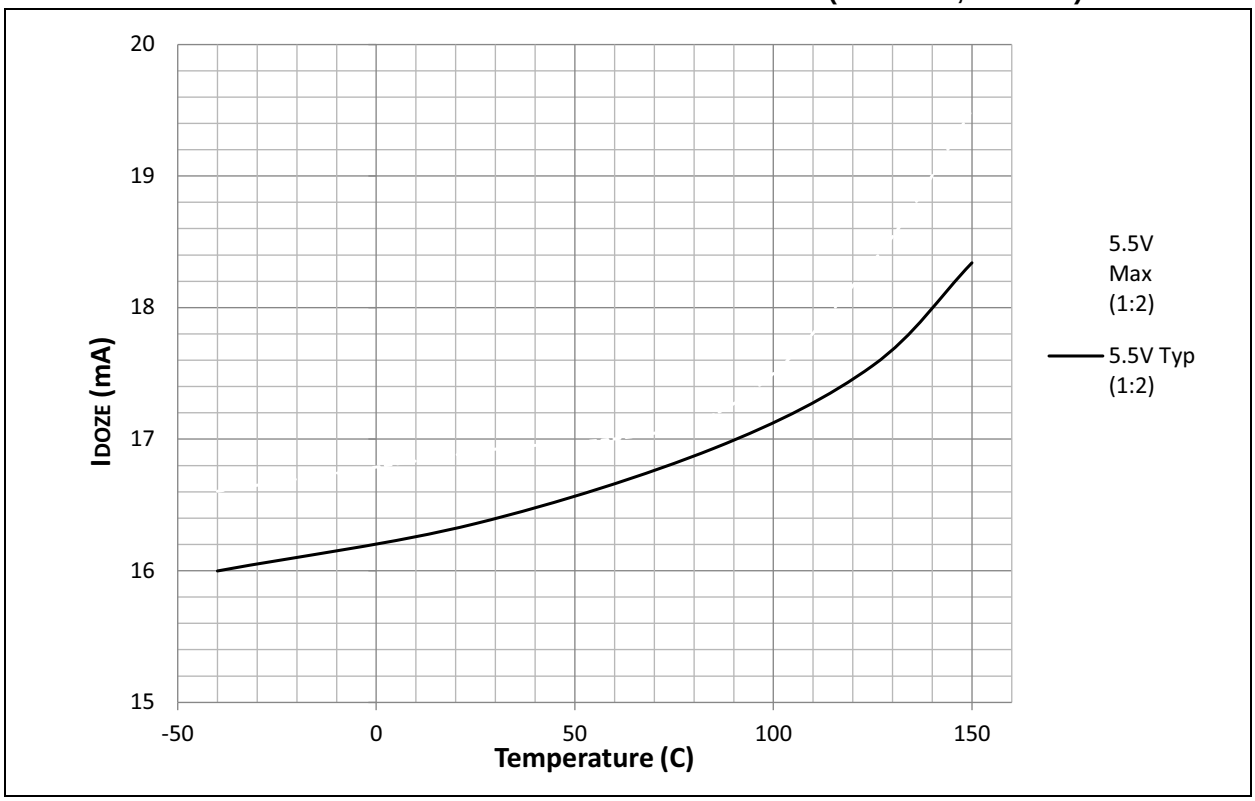
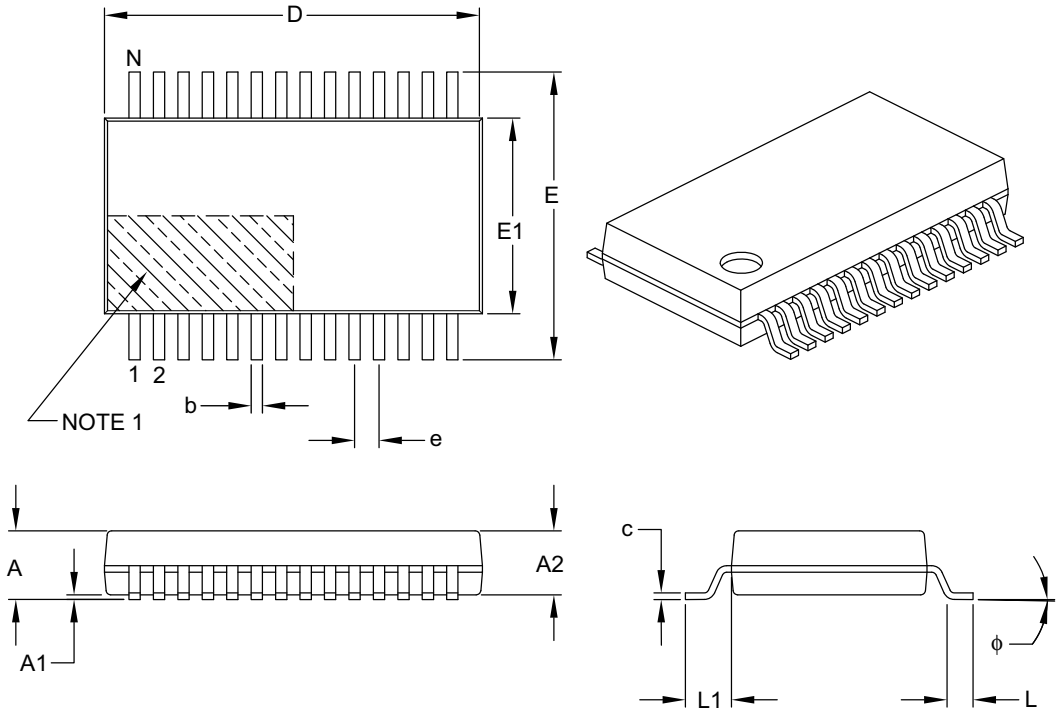


FIGURE 33-10: TYPICAL/MAXIMUM IDOZE vs. TEMPERATURE (DOZE 1:2, 70 MIPS)



28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

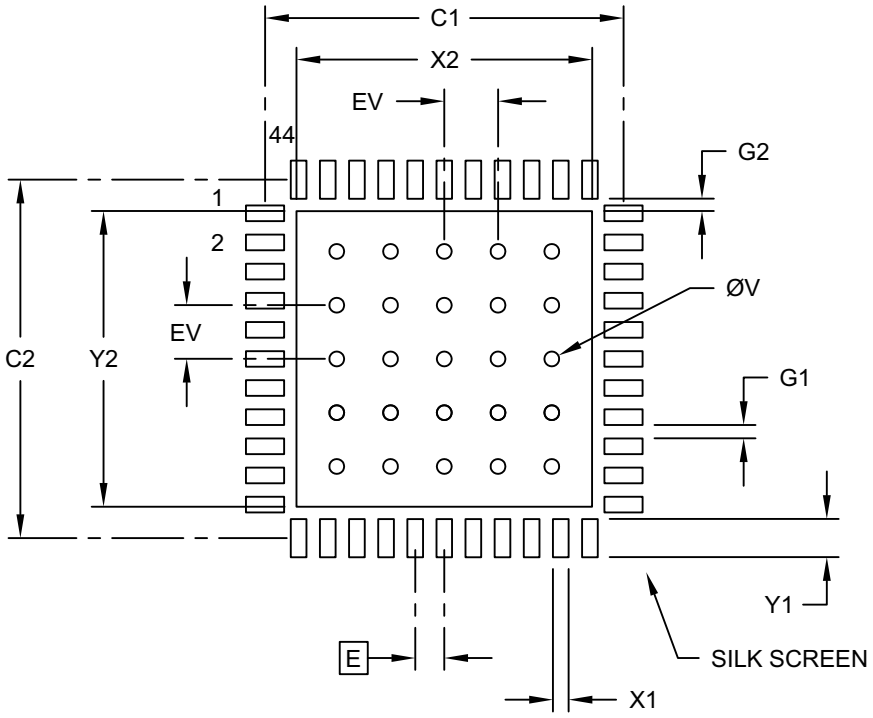
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN or VQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	X2			6.60
Optional Center Pad Length	Y2			6.60
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.85
Contact Pad to Contact Pad (X40)	G1	0.30		
Contact Pad to Center Pad (X44)	G2	0.28		
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		1.20	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing No. C04-2103C

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